Buildup for Mindteck
mind-13jun2k11-11695

0.0350	copper plating layer 1		
0.0175	copper foil layer1	Signal	7.9167 mil traces 40 ohms single ended 5.0126 mil traces 50 ohms single ended 6.0088 mil traces 5.9912 mil seperation 80 ohms differential 3.9356 mil traces 8.0644 mil seperation 100 ohms differential
	Prepreg 1-2		
0.0350	copper foil layer 2	Plane	
	Core 2-3		
0.0350	copper foil layer 3	Signal	7.8354 mil traces 40 ohms single ended 5.0352 mil traces 50 ohms single ended 6.2841 mil traces 5.7159 mil seperation 80 ohms differential 4.2005 mil traces 7.7995 mil seperation 100 ohms differential
	Prepreg 3-4		
0.0350	copper foil layer 4	Plane	
	Core 4-5		
0.0350	copper foil layer 5	Plane	
	Prepreg 5-6		
0.0350	copper foil layer 6	Signal	7.8354 mil traces 40 ohms single ended 5.0352 mil traces 50 ohms single ended 6.2841 mil traces 5.7159 mil seperation 80 ohms differential 4.2005 mil traces 7.7995 mil seperation 100 ohms differential
	core 6-7		
0.0350	copper foil layer 7	Plane	
	prepreg 7-8		
0.0175	copper foil layer 8	Signal	7.9167 mil traces 40 ohms single ended 5.0126 mil traces 50 ohms single ended 6.0088 mil traces 5.9912 mil seperation 80 ohms differential 3.9356 mil traces 8.0644 mil seperation 100 ohms differential
0.0350	copper plating layer 8		
1.6000	total pcb thickness in mm		

Disclaimer: This stack-up has assumptions regarding the copper area per layer, as well as prepreg distance & dielectric constants. An impedance tolerance of +/- 10% can only be achieved if we adjust the trace width & prepreg height to meet the impedance requirement after receipt of the gerber files.